

**AMENDMENTS TO THE CLAIMS**

1. (Previously presented): A cutting apparatus comprising:
  - a support for holding a wafer having a protective tape thereon;
  - a cutting element placed at a first predetermined distance from said support for moving relative to said support to cut a portion of the protective tape from the wafer when the wafer is placed on the support;
  - a sensor comprising a means ~~detector~~ for detecting if the portion of the protective tape on a wafer is ~~properly~~ removed by said cutting element, said ~~detector~~ sensor being positioned behind said cutting element relative to said first predetermined distance from the perimeter of said wafer and relative to said protective tape to perform the detecting;
  - a transport mechanism ~~for~~ capable of moving the wafer from the support to a grinding apparatus if the portion of the protective tape on the wafer is properly removed; and
  - a circuit comprising a means for initiating corrective action to stop the transport mechanism from moving the wafer to the grinding apparatus when the sensor detects that the protective tape is not ~~properly~~ removed from a wafer by said cutting element, wherein said sensor is coupled to said circuit.
2. (Original): The apparatus of claim 1, wherein the circuit for initiating corrective action stops operation of said cutting apparatus.
3. (Canceled)

4. (Original): The apparatus of claim 1, wherein the circuit for initiating corrective action prevents a backgrinding apparatus from grinding the wafer.

5. (Previously presented): The apparatus of claim 1, wherein said detector comprises a mechanical element for detecting said tape.

6. (Canceled)

7. (Previously presented): The apparatus of claim 1, wherein said first predetermined distance is approximately 0.5 mm from the edge of the wafer when the wafer is placed on said support.

Claims 8-15 (Canceled)